



**31st International Conference on Electronics Manufacturing and Technology
(IEMT 2006)
8 - 10 November 2006, Kuala Lumpur, Malaysia**

FIRST ANNOUNCEMENT AND CALL FOR PAPERS



About IEMT

The 31st Electronics Manufacturing Technology Conference (IEMT 2006) is an international event organized by the IEEE CPMT Malaysia Chapter with co-sponsorship from CPMT society of IEEE, Santa Clara Chapter. IEMT 2006 will feature short courses, 3 parallel technical sessions, and exhibition. It aims to provide good coverage of technological developments in all areas of electronics packaging, from design to manufacturing and operation. IEMT 2006 is a major forum, providing opportunities to network and meet leading experts in addition to exchange of up to date knowledge in the field. Since 1997, IEMT has gained a reputation as a premier electronics materials and packaging conference and is well attended by experts in all aspects related to packaging technology from all over the world.

Conference Topics

The topics of interests are specific to micro systems/MEMS, their packaging, electronics materials and reliability issues. Extended abstracts are being sought from, but not limited to, the following areas:

- Emerging Packaging Technologies
- Advanced Packaging
- Interconnection Technologies
- Manufacturing Technologies
- IC Testing Technology
- Materials & Processes
- MEMS Packaging
- Electrical Modeling & Signal Integrity
- Thermal Characterization & Cooling Solutions
- Mechanical Modeling & Structural Integrity
- Quality & Reliability
- Chip-Scale Packaging/Flip Chip

Important Dates:

Submission of Abstract	10 May 2006
Notification of Acceptance	30 May 2006
Submission of Manuscript	15 August 2006

Extended Abstract and Paper Submission

Extended abstracts are invited to describe original and unpublished work. The extended abstract should be about 500 words stating clearly the purpose, methodology, results, and conclusions of the work. Key references to prior publications and how the work enhances the existing knowledge should be included in the extended abstract. Authors are requested to designate appropriate areas for the purpose of abstract review. All submissions must be in English and should be made via electronic mail to conference secretariat. Author may send their abstract either in MS Word or Adobe Acrobat® PDF format with only one single file for each submission.

The abstracts must be sent to **secretariat** via email by 10 May, 2006. Authors are requested to include their affiliation, mailing address, telephone and fax numbers, and e-mail address. Authors will be notified of paper acceptance and instruction for preparing final papers by 30 May 2006. The final manuscript for publication in the conference proceedings is due by 15 August 2006.

Short Courses:

The conference will include short courses, which will be conducted by leading experts in the field. Details will be provided in the conference website and available in subsequent mailings.

Exhibition:

A tabletop exhibition from suppliers of materials, equipment, components, software, and service providers of electronics industries will also be held at the venue of the conference.

Conference Information and Contacts

General Chair	Technical Chairs		
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Short Course Chairs	Logistic/Publication/Facility	Secretariat	
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